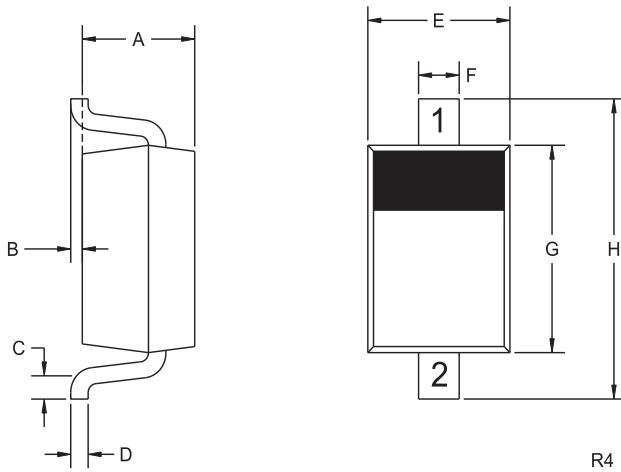


Package Details
SOD-323 Case



Mechanical Drawing



SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.031	0.039	0.80	1.00
B	0.000	0.004	0.00	0.10
C	0.008	-	0.20	-
D	0.004	0.007	0.11	0.19
E	0.045	0.053	1.15	1.35
F	-	0.014	-	0.35
G	0.063	0.071	1.60	1.80
H	0.094	0.102	2.40	2.60

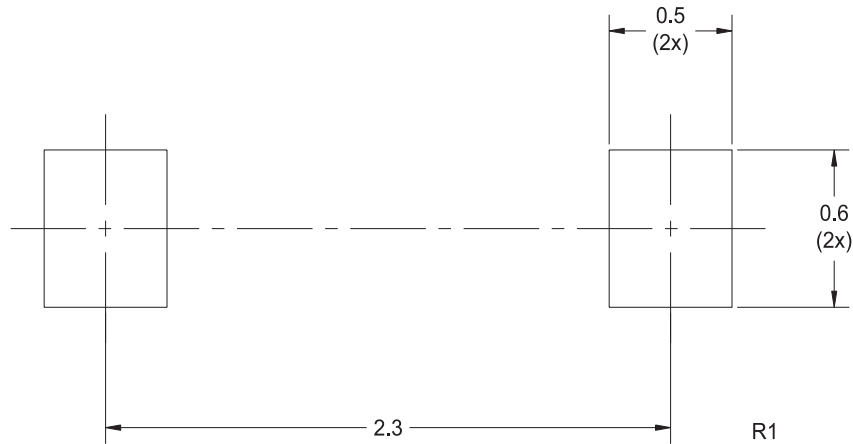
SOD-323 (REV: R4)

Lead Code:

- 1) Cathode
- 2) Anode

Part Marking: 2-3 Character Alpha/Numeric Code

Mounting Pad Geometry (Dimensions in mm)



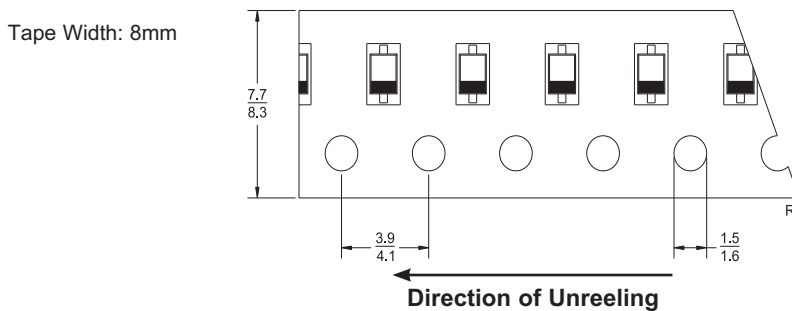
R3 (4-March 2010)

Package Details

SOD-323 Case



Tape Dimensions and Orientation (Dimensions in mm)



Devices are taped in accordance with Electronic Industries Association Standard EIA-481-1-A

Packaging Base

7" Reel = 3,000 pcs.

Reel Labeling Information

Each reel is labeled with the following information:

Central Part Number, Customer Part Number, Purchase Order Number, Quantity, Lot Number, Date Code, Ship Date and Marking Code.

Reel Packing Information

Reel Size	Reels per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
7"	9	27,000	9x9x5	23x23x13	3	2
	18	54,000	9x9x9	23x23x23	6	3
	40	120,000	21x9x9	53x23x23	13	6
	108	324,000	27x9x17	69x23x43	34	16

Ordering Information

- For devices taped and reeled on 7" reels, add TR suffix to part number.
- All SMDs are available in small quantities for prototype and manual placement applications.

R3 (4-March 2010)

Material Composition Specification

SOD-323 Case



Device average mass **4.9 mg**
 Fluctuation margin **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	1.43%	0.07	Si	7440-21-3	1.43%	0.07	14,286
bond wire	gold	0.2%	0.01	Au	7440-57-5	0.2%	0.01	2,041
leadframe	copper w/ silver plating	22.82%	1.118	Cu	7440-50-8	22.37%	1.096	223,673
				Ag	7440-22-4	0.45%	0.022	4,490
encapsulation*	EMC	71.55%	3.506	silica	7631-86-9	51.59%	2.528	515,918
				epoxy resin	Proprietary	17.96%	0.88	179,592
				Sb ₂ O ₃	1309-64-4	1.43%	0.07	14,286
				TBBA	79-94-7	0.37%	0.018	3,673
				carbon black	1333-86-4	0.2%	0.01	2,041
	EMC GREEN	71.55%	3.506	silica	60676-86-0	47.63%	2.334	476,327
				epoxy resin	29690-82-2	11.04%	0.541	110,408
				phenol resin	9003-35-4	5.53%	0.271	55,306
				carbon black	1333-86-4	0.2%	0.01	2,041
				metal hydroxide	1309-42-8	7.14%	0.35	71,429
plating**	tin/lead process	4.0%	0.196	Sn	7440-31-5	3.41%	0.167	34,082
				Pb	7439-92-1	0.59%	0.029	5,918
	matte tin	4.0%	0.196	Sn	7440-31-5	4.0%	0.196	40,000

*EMC GREEN molding compound is Halogen-Free.

**For Lead Free plating, add suffix "PB FREE" to part number.

For Tin/Lead plating, add suffix "TIN/LEAD" to part number.

No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R8 (16-July 2018)